

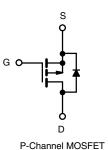
P-Channel 60 V (D-S) 175 °C MOSFET

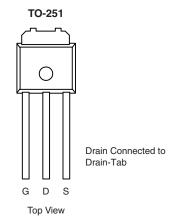
PRODUCT SUMMARY				
V _{DS} (V)	- 60			
$R_{DS(on)}(\Omega)$ at $V_{GS} = -10 \text{ V}$	0.0135			
$R_{DS(on)}(\Omega)$ at $V_{GS} = -4.5 \text{ V}$	0.017			
I _D (A)	- 50			
Configuration	Single			

FEATURES

- TrenchFET® Power MOSFET
- Package with Low Thermal Resistance
- 100 % R_g and UIS Tested







ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V_{DS}	- 60	V	
Gate-Source Voltage		V_{GS}	± 20] v	
Continuous Drain Currenta	T _C = 25 °C	1	- 50		
Continuous Drain Current	T _C = 125 °C	Ι _D	- 38		
Continuous Source Current (Diode Conduction) ^a	Is	- 50	Α		
Pulsed Drain Current ^b	I _{DM}	- 200			
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	- 52		
Single Pulse Avalanche Energy	L=0.1 MH	E _{AS}	135	mJ	
Maximum Power Dissipation ^b	T _C = 25 °C	P _D	136	W	
	T _C = 125 °C	r _D	45	VV	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to + 175	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-Ambient	PCB Mount ^c	R_{thJA}	50	°C/W		
Junction-to-Case (Drain)		R_{thJC}	1.1	C/ VV		

Notes

- a. Package limited.
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- c. When mounted on 1" square PCB (FR-4 material).



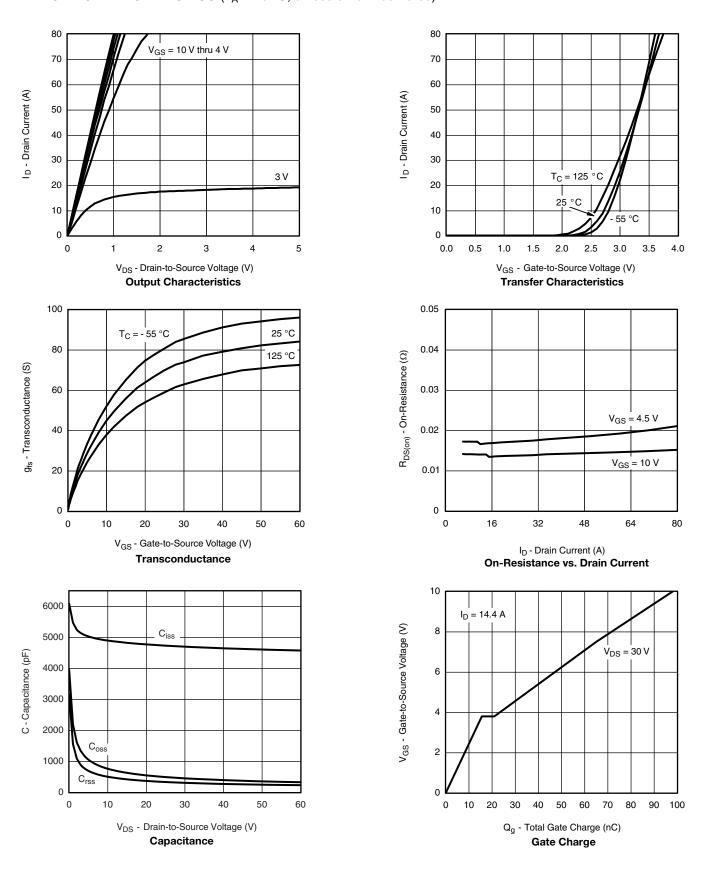
SPECIFICATIONS (T _C = 25 °C, unless otherwise noted)								
PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT		
Static								
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		- 60	-	-	V	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_D = -250 \mu A$			- 2.5	v	
Gate-Source Leakage	I _{GSS}	V _{DS} =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nA	
		$V_{GS} = 0 V$	V _{DS} = - 60 V	-	-	- 1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V	V _{DS} = - 60 V, T _J = 125 °C	-	-	- 50	μΑ	
		V _{GS} = 0 V	V _{DS} = - 60 V, T _J = 175 °C	-	-	- 150		
On-State Drain Current ^a	I _{D(on)}	V _{GS} = - 10 V	V _{DS} ≥ - 5 V	- 50	-	-	Α	
		V _{GS} = - 10 V	I _D = - 17 A	-	0.0135	-	Ω	
		V _{GS} = - 10 V	I _D = - 50 A, T _J = 125 °C	-	0.026	=		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V	I _D = - 50 A, T _J = 175 °C	-	0.032	-		
		V _{GS} = - 4.5 V	I _D = - 14 A	-	0.017	-		
Forward Transconductancea	9 _{fs}	V _{DS} = - 15 V, I _D = - 17 A		-	50	-	S	
Dynamic ^b								
Input Capacitance	C _{iss}			-	4730	5910		
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	V _{DS} = - 25 V, f = 1 MHz	-	485	606	pF	
Reverse Transfer Capacitance	C _{rss}	1		-	330	410		
Total Gate Charge ^c	Qg			-	98	150		
Gate-Source Charge ^c	Q _{gs}	V _{GS} = - 10 V	$V_{DS} = -30 \text{ V}, I_{D} = -50 \text{ A}$	-	15	23	nC	
Gate-Drain Charge ^c	Q_{gd}	7		-	21	32		
Gate Resistance	Rg		f = 1 MHz		2.9	4.42	Ω	
Turn-On Delay Time ^c	t _{d(on)}				15	18		
Rise Time ^c	t _r	V_{DD} = - 30 V, R_L = 0.6 Ω $I_D \cong$ - 50 A, V_{GEN} = - 10 V, R_g = 6.0 Ω		-	12	16	ns	
Turn-Off Delay Time ^c	t _{d(off)}			-	112	125		
Fall Time ^c	t _f	7	-	39	48	1		
Source-Drain Diode Ratings and Characteristics ^b								
Pulsed Current ^a	I _{SM}			-	-	- 200	Α	
Forward Voltage	V _{SD}	I _F =	-	- 0.8	- 1.5	V		

Notes

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

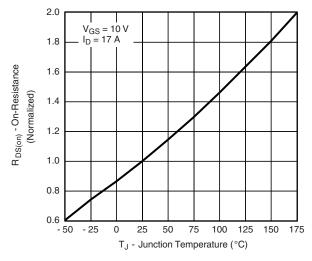


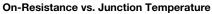
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

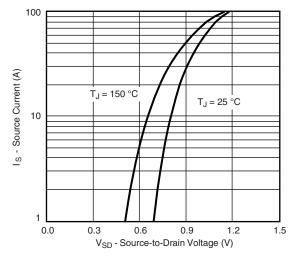




TYPICAL CHARACTERISTICS ($T_A = 25$ °C, unless otherwise noted)

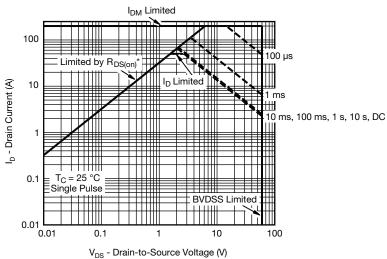






Source Drain Diode Forward Voltage

THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)

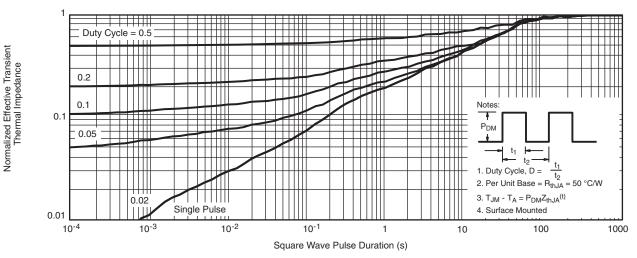


* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

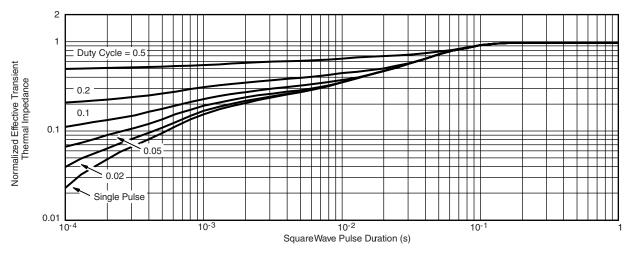
Safe Operating Area



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

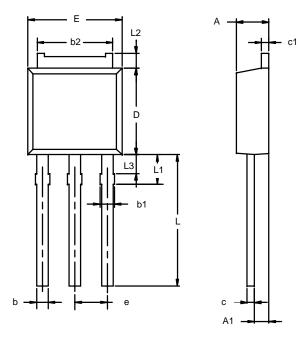
Note

- The characteristics shown in the two graphs
- Normalized Transient Thermal Impedance Junction to Ambient (25 °C)
- Normalized Transient Thermal Impedance Junction to Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



TO-251AA



Note:	Dimension	1.3 is 1	for r	eference	only

	MILLIN	IETERS	INC	IES	
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
c1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
Е	6.48	6.73	0.255	0.265	
е	2.28 BSC		0.090	BSC	
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	



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